
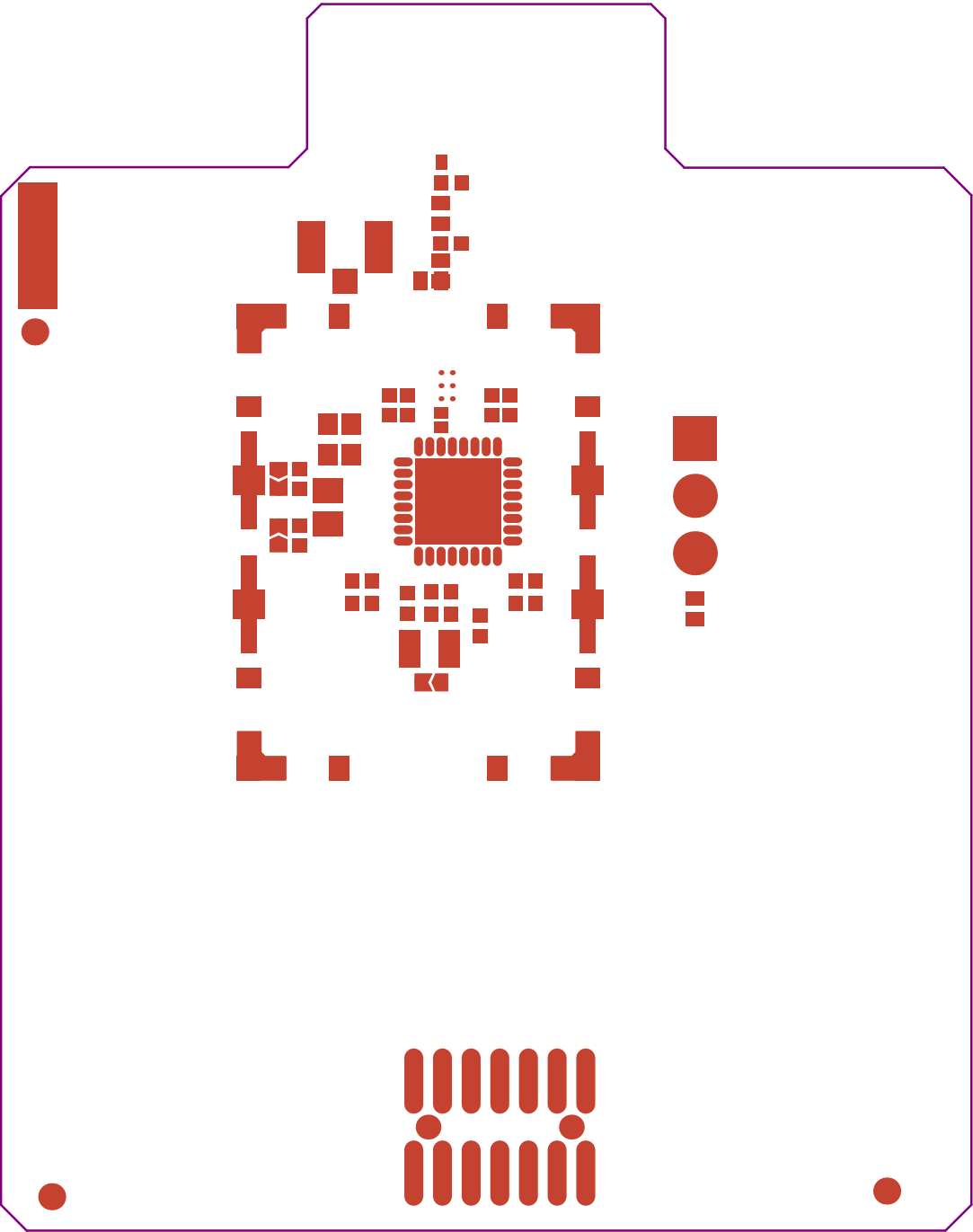

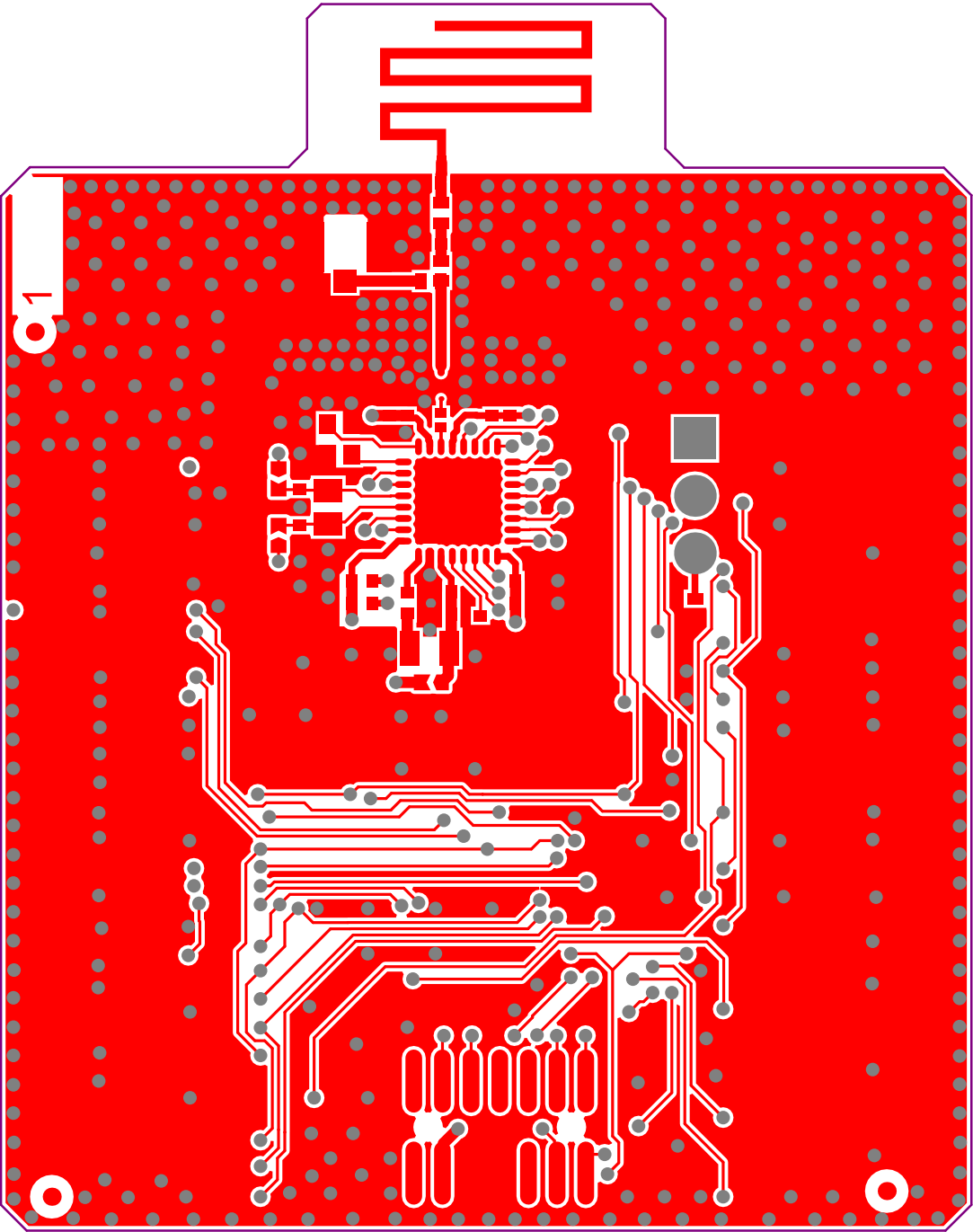



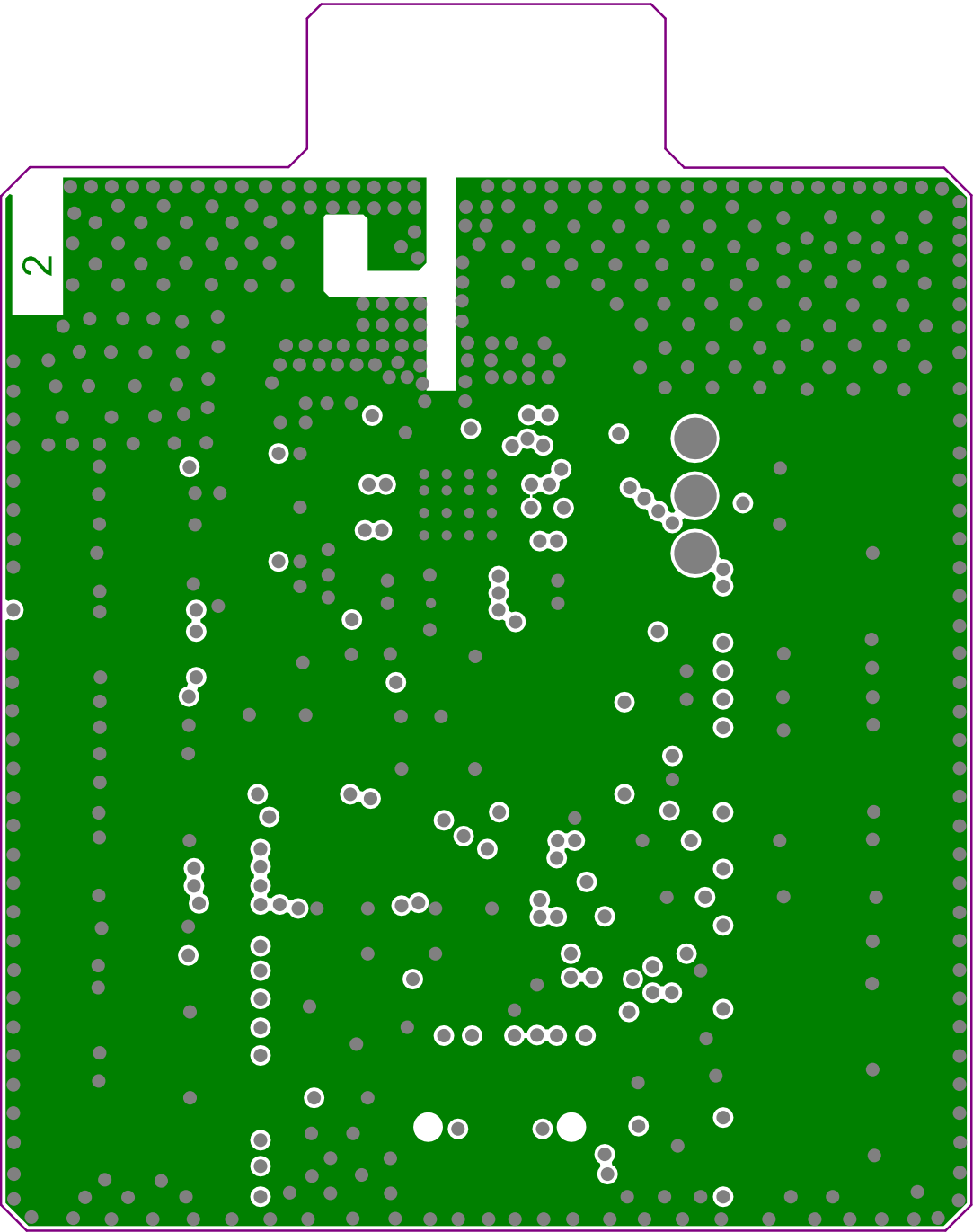
Project: Miniboard for STM32WB09		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	




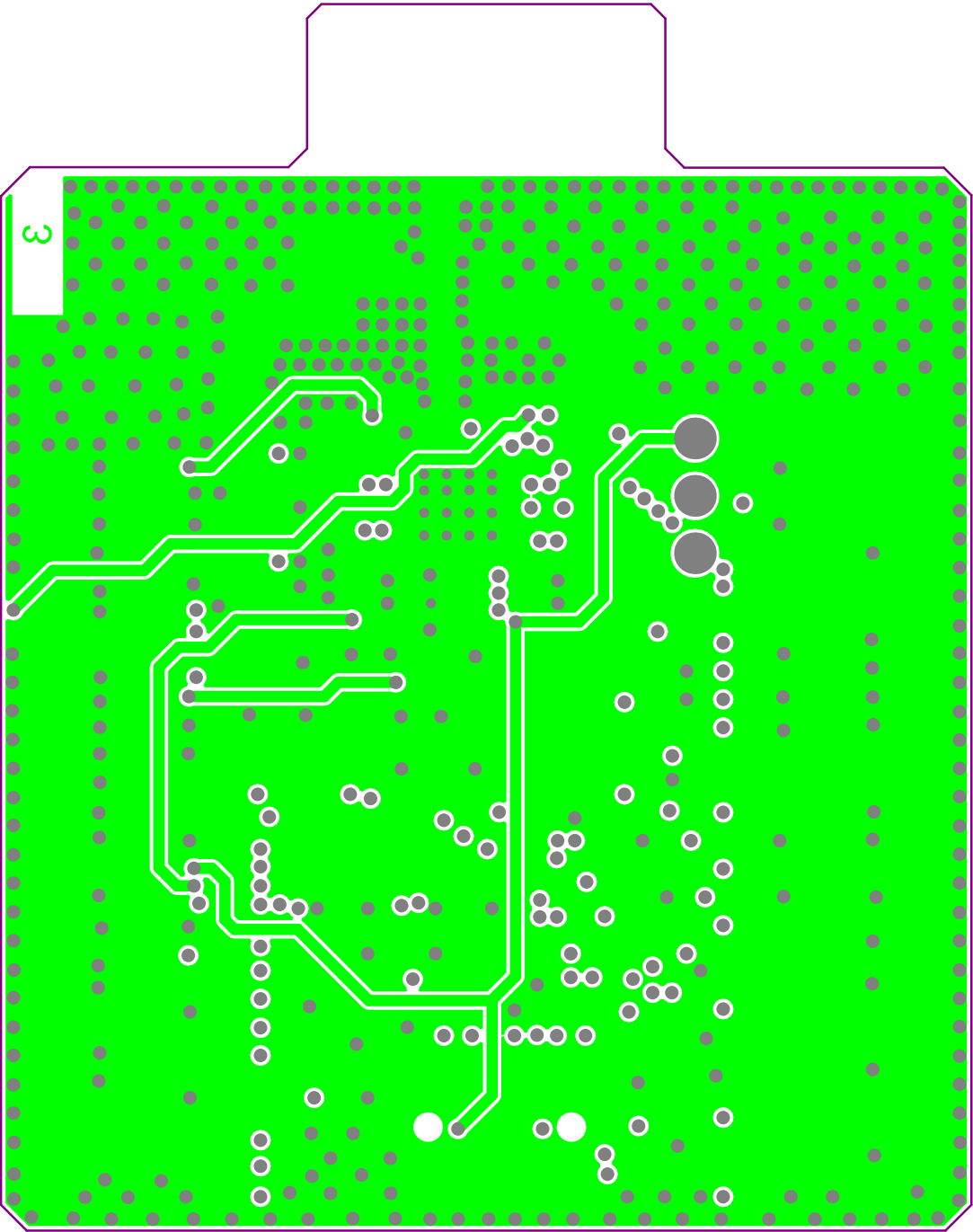
Project: Miniboard for STM32WB09		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	





Project: Miniboard for STM32WB09		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	

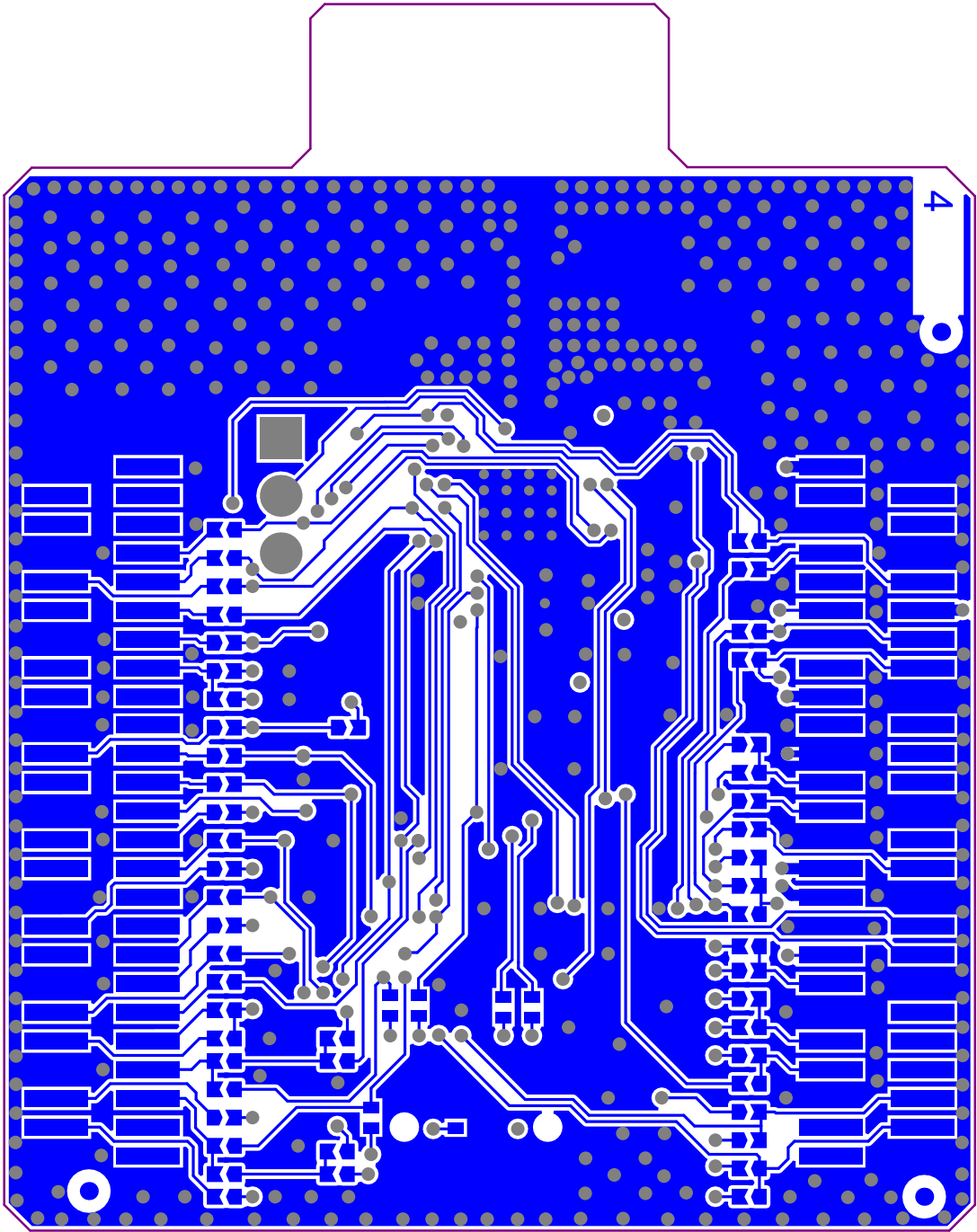


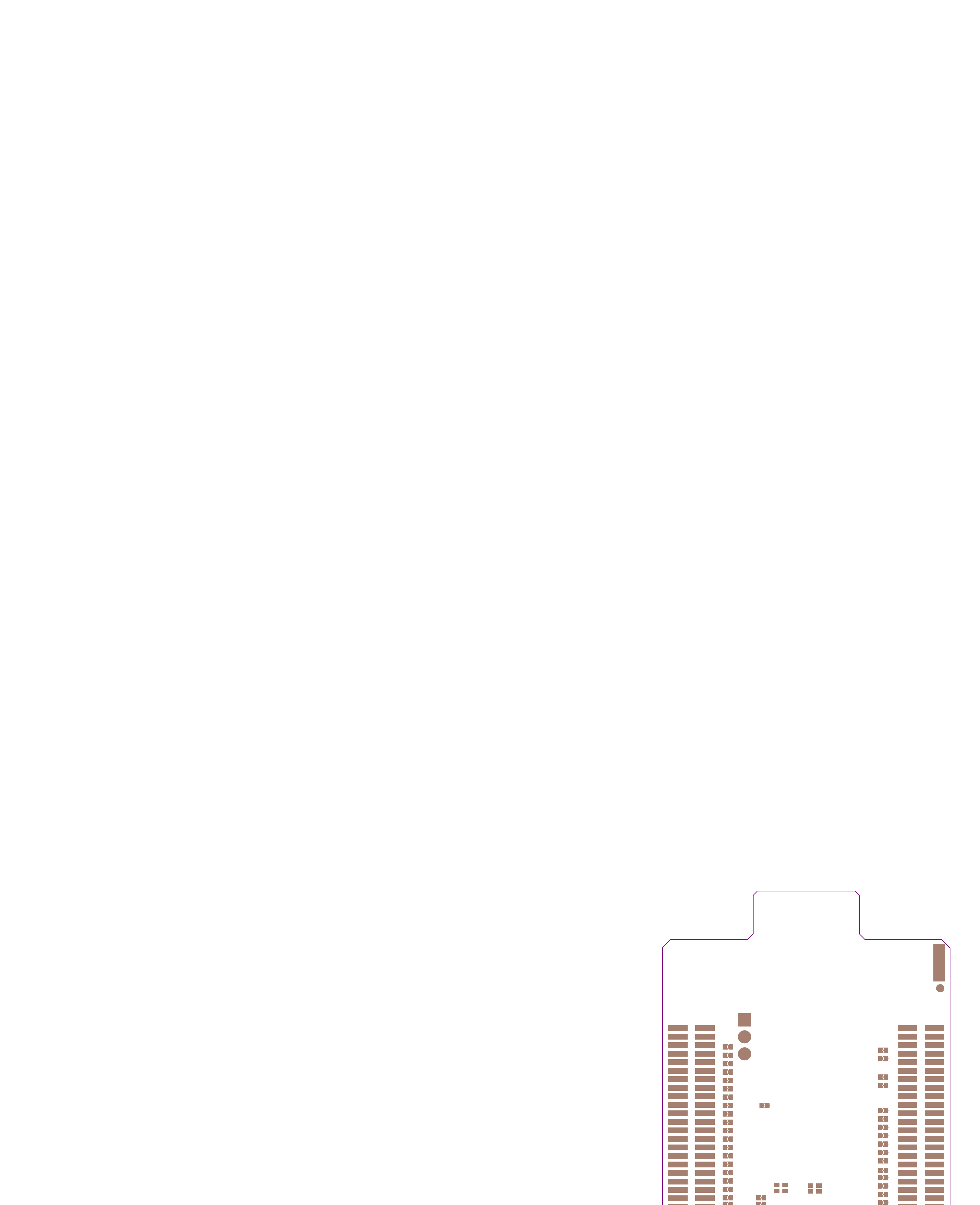
Project: Miniboard for STM32WB09		
Layer: Internal 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	




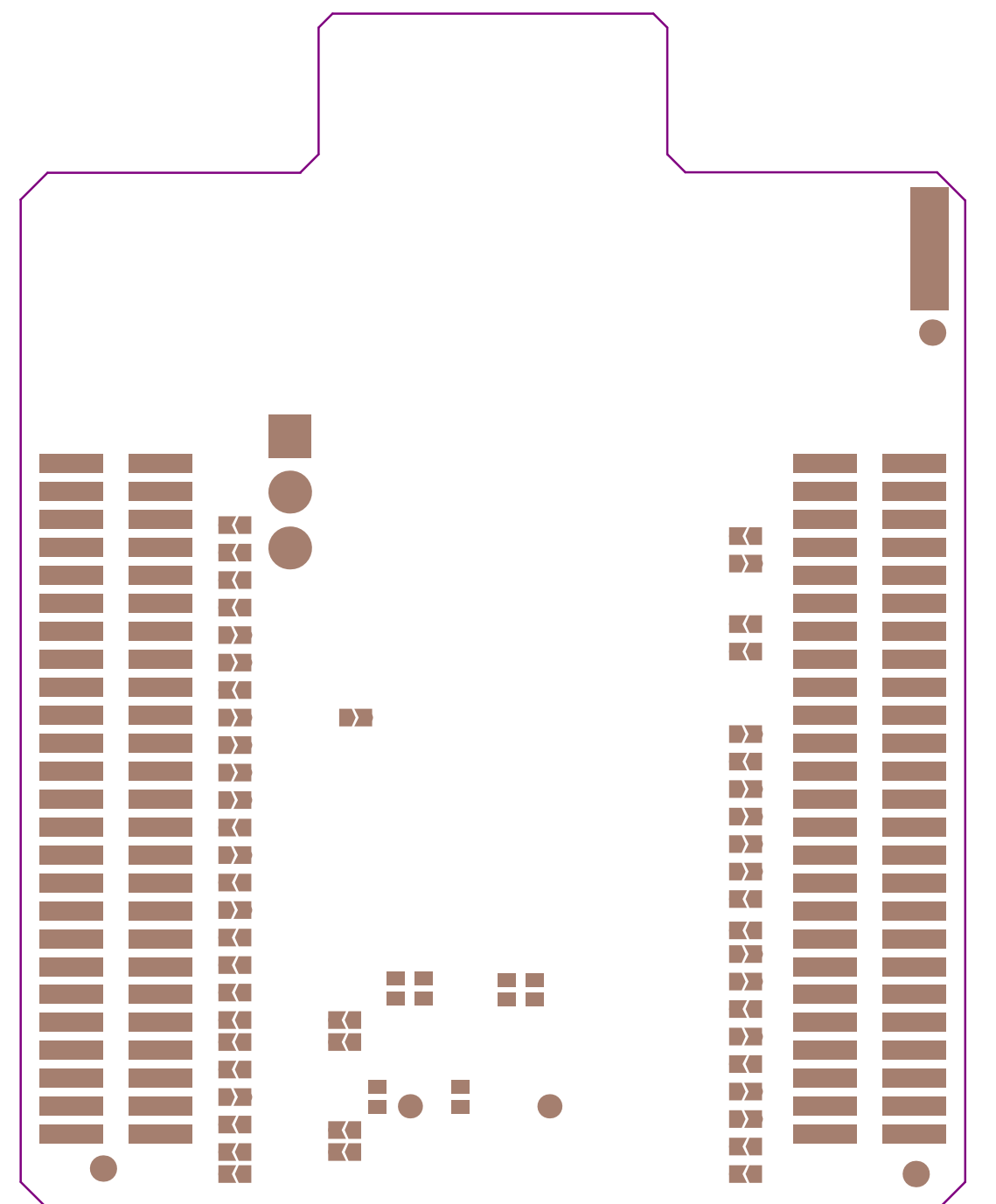
Project: Miniboard for STM32WB09		
Layer: Internal 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	


Project: Miniboard for STM32WB09		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	

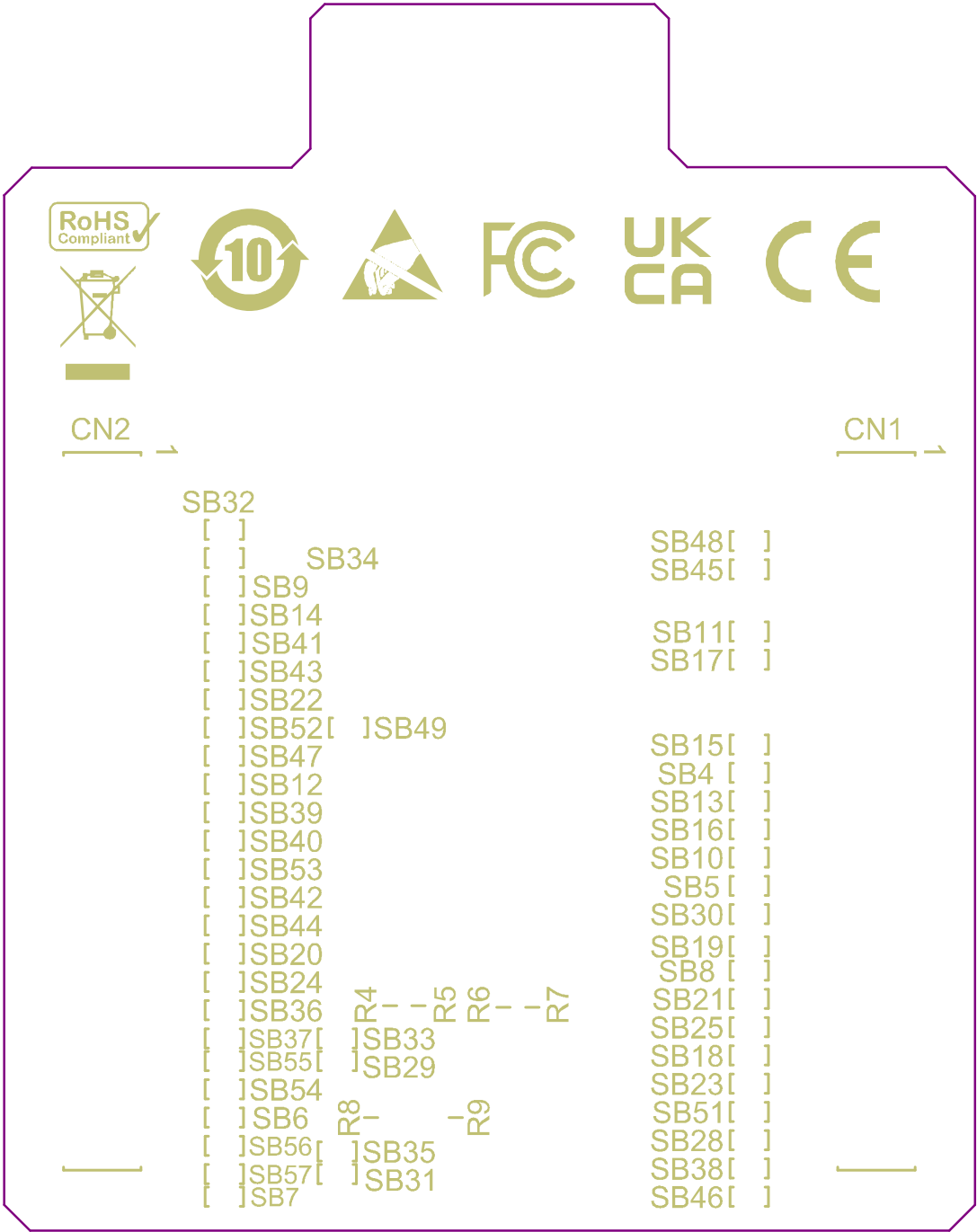




Project: Miniboard for STM32WB09		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	



Project: Miniboard for STM32WB09		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	



IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	19.685	5.708	50 ohm	NA	+/- 10%
TOP	5.905	5.708	50 ohm	NA	+/-10%

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

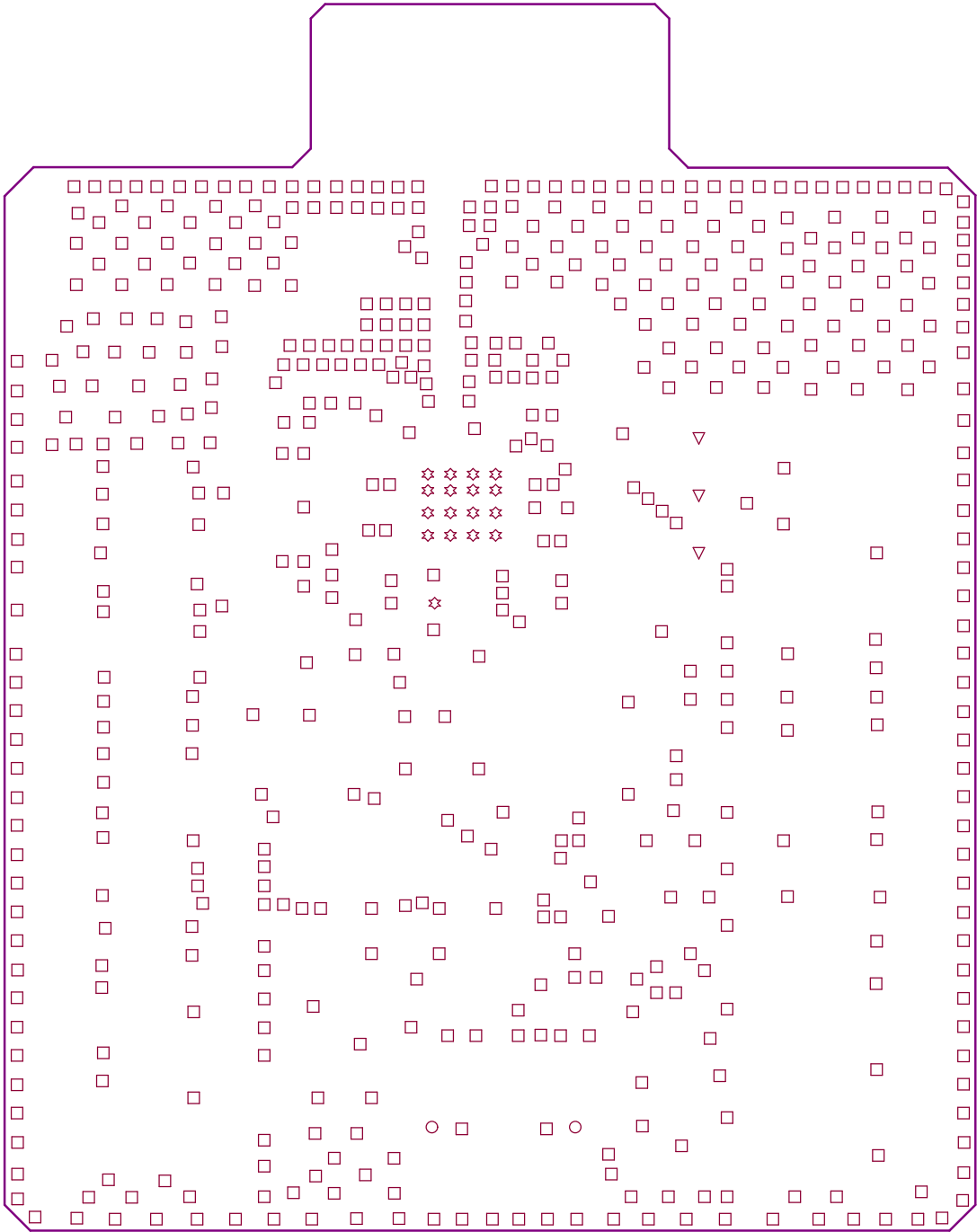
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.


☐ H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3.5	
1	Top Layer		0,042mm		
	Dielectric 1	FR-4	0,106mm	4.2	
2	Internal 1		0,035mm		
	Dielectric 3		1,248mm	4.2	
3	Internal 2		0,035mm		
	Dielectric 2		0,106mm	4.2	
4	Bottom Layer		0,042mm		
	Bottom Solder	Solder Resist	0,015mm	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description
✱	17	0,20mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v45h20m0mx0	
□	564	0,30mm (11,81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30m0mx0	
○	2	1,00mm (39,37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn100m105p-1	
▽	3	1,00mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	
	586 Total								



Project: Miniboard for STM32WB09		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB2032	
Date: 09 June 2023	Rev: B	